

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
 Contact Info: ti.com/support
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
 Created on: 05/09/2022

Details for "SN74LV175ADR"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
SN74LV175ADR	NIPDAU	Level-1-260C-UNLIM	TI AGUASCALIENTES	D 16	3.91x9.9x1.58	194.5

*Total Device Mass
 The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Copper and Its Alloys	Copper	7440-50-8	0.073698	99.998643	999986	0.037897	379
Precious Metals	Silver	7440-22-4	0.000001	0.001357	14	0.000001	0
Sub-Total			0.073699	100	1000000	0.037897	379
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	0.176797	78.999884	789999	0.090912	909
Thermoplastics	Epoxy	85954-11-6	0.046997	21.000116	210001	0.024167	242
Sub-Total			0.223794	100	1000000	0.115078	1151
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	79.065844	97.24	972400	40.656843	406568
Copper and Its Alloys	Iron	7439-89-6	2.11406	2.6	26000	1.087081	10871
Copper and Its Alloys	Phosphorus	7723-14-0	0.121965	0.15	1500	0.062716	627
Other Nonferrous Metals and Alloys	Lead	7439-92-1	0.008131	0.01	100	0.004181	42
Sub-Total			81.31	100	1000000	41.810822	418108
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	0.66584	95.12	951200	0.342385	3424
Precious Metals	Gold	7440-57-5	0.00546	0.78	7800	0.002808	28
Precious Metals	Palladium	7440-05-3	0.0287	4.1	41000	0.014758	148
Sub-Total			0.7	100	1000000	0.359951	3600
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	97.987878	87.999999	880000	50.386837	503868
Other Plastics and Rubber	Carbon Black	1333-86-4	0.33405	0.3	3000	0.171774	1718
Other Plastics and Rubber	Organic Phosphorus	1330-78-5	0.612424	0.55	5500	0.314918	3149
Thermoplastics	Epoxy	85954-11-6	12.41551	11.15	111500	6.384242	63842
Sub-Total			111.349862	100	1000000	57.25777	572578
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	0.813828	100	1000000	0.418483	4185
Sub-Total			0.813828	100	1000000	0.418483	4185
Total			194.471183			100	1000000

Important Note
 The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.
 The ppm calculations are at the component level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the component.
[See Glossary of Terms for more details.](#)

Important Part Information
 There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSI or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology
[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."
[For additional information, please contact TI customer support.](#)

Signature: [\(click here for a fuller statement with a signed certificate\)](#)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality
 For further environmental statements, please go to www.ti.com/ecoinfo
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RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide [Sb2O3] contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.